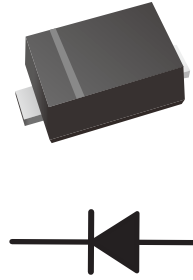


Switching Diode

Features

- General purpose diodes
- Fast switching devices
- SOD923 Micro SMD package
- Matte Tin (Sn) Lead finish
- Cathode Band / Device
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case:SOD-923
- Polarity: Color band denotes cathode end
- Tape specification:Conductive

Ordering Information

Part Number	Marking	Shipping	Reel
LT4148M9-TR8	S1	8000PCS Tape&Reel	7 inches

Maximum Ratings (Ta = 25 °C)

Symbol	Parameter	Value	Units
V_{RSM}	Non-Repetitive Peak Reverse Voltage	100	V
V_{RRM}	Repetitive Peak Reverse Voltage	85	V
I_{FRM}	Repetitive Peak Forward Current	300	mA
I_{FSM}	Non-Repetitive Peak Forward Current *1	2	A
I_o	Continuous Forward Current	100	mA
P_D	Power Dissipation	200	mW
T_J	Junction Temperature	150	°C
T_{STG}	Storage Temperature	-55 to +150	°C

*1 Pulse width = 1μs

Electrical Characteristics (Ta = 25 °C)

Symbol	Parameter	Conditions	Min	Max	Units
BV_R	Breakdown Voltage	$I_R = 100\mu A$	100		V
I_R	Reverse Current	$V_R = 20V$ $V_R = 80V$		25 100	nA nA
V_F	Forward Voltage	$I_F = 10mA$ $I_F = 100mA$		1.0 1.2	V V
C	Capacitance	$V_R = 0V, f = 1MHz$		4	pF
T_{RR}	Reverse Recovery Time	$I_F = 10mA, V_R = 6V$ $I_{RR} = 1mA, R_L = 100\Omega$		4	ns



Characteristics Curves

Fig.1 Typical Instantaneous Forward Characteristics

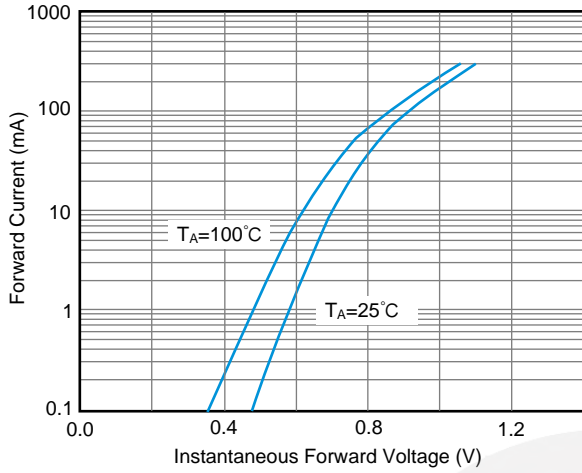


Fig.2 Typical Reverse Leakage Characteristics

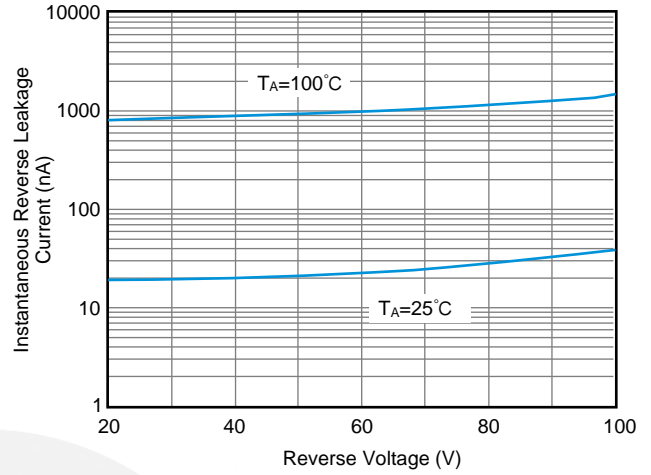


Fig.3 Capacitance Characteristics

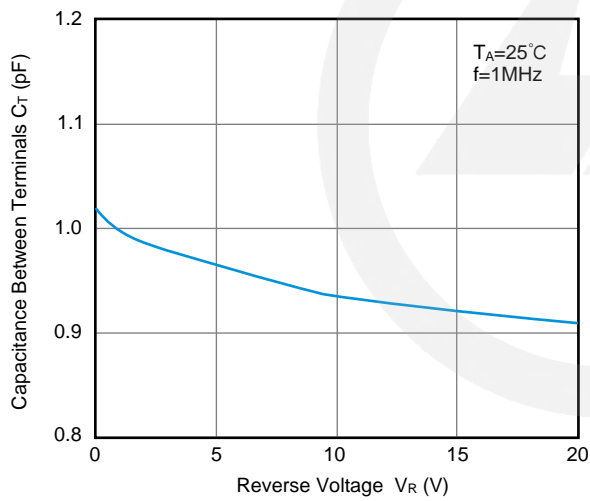
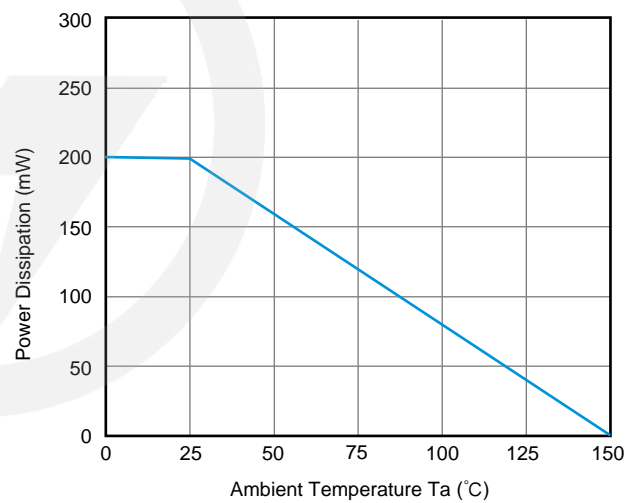
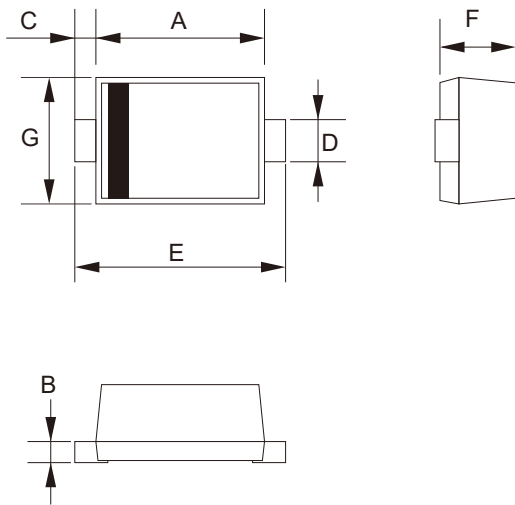


Fig.4 Power Derating Curve



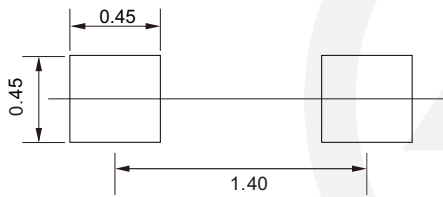
SOD-923 Package Outline



Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.700	0.900
B	0.050	0.200
C	0.050	0.150
D	0.150	0.300
E	0.090	1.100
F	0.340	0.450
G	0.550	0.650

SOD-923 Suggested Pad Layout

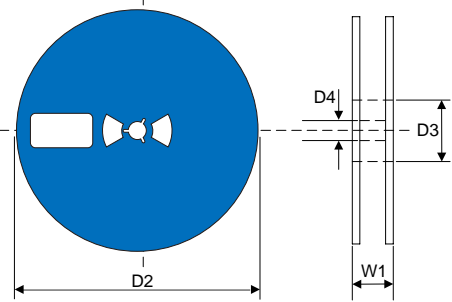


Note:

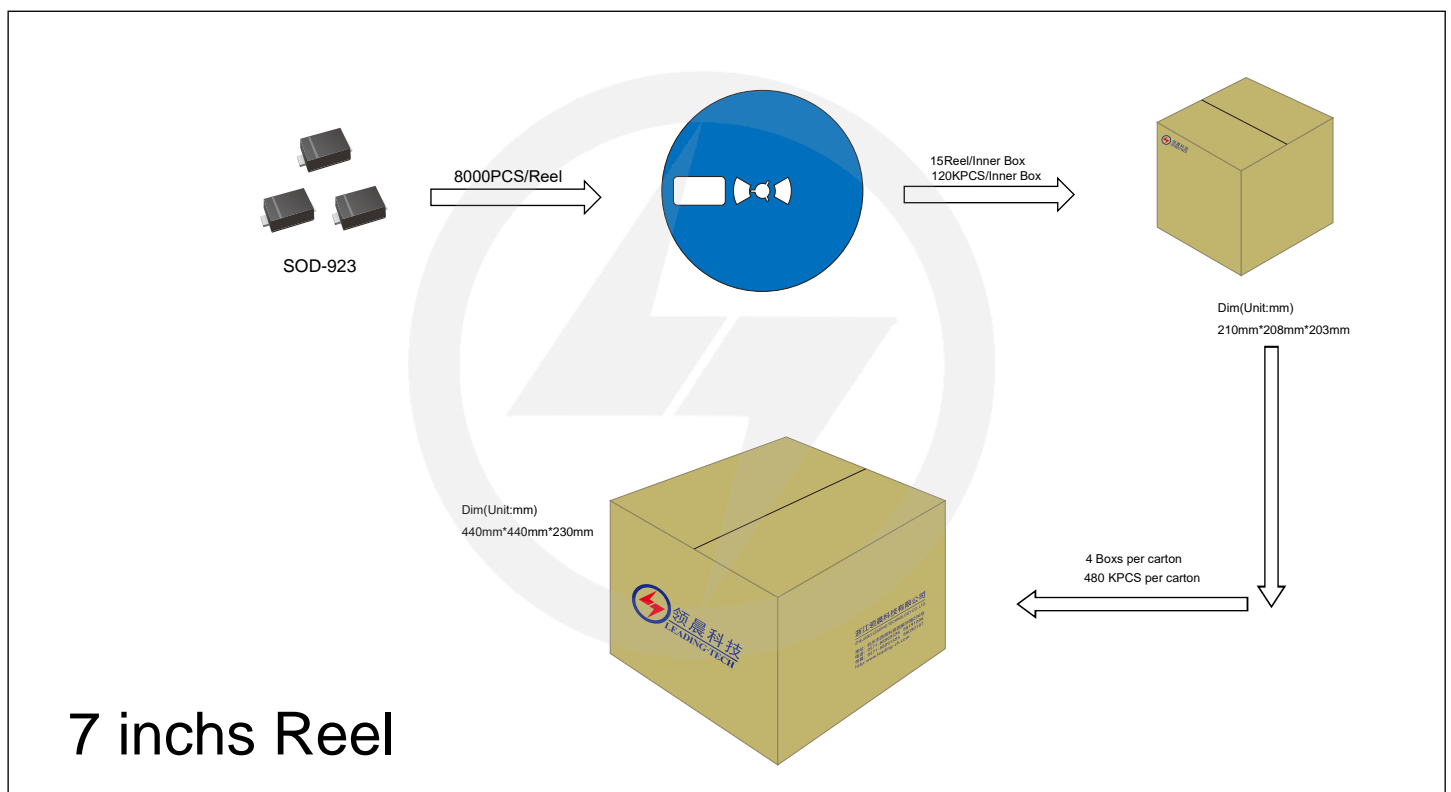
1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

Reel Dimensions

Unit : mm

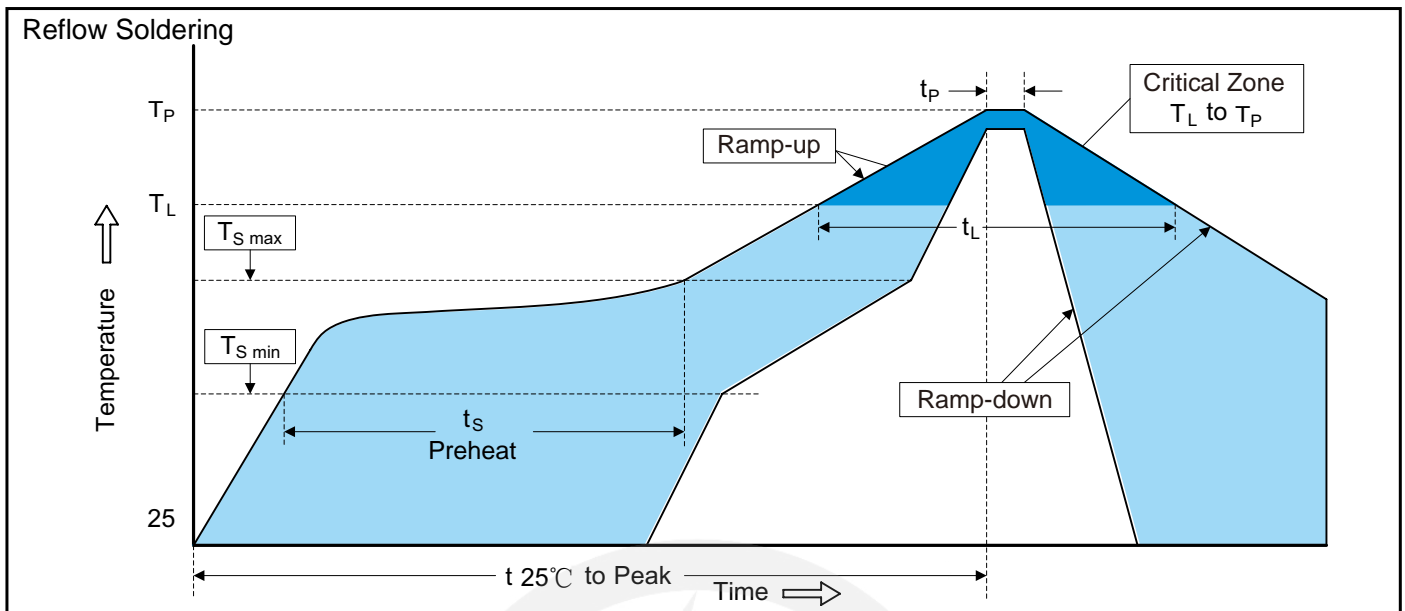
<p>7" Reel</p> 	D2	$\Phi 178.0 \pm 2.0$
	D3	$\Phi 50$
	D4	13.0 ± 0.5
	W1	12 ± 0.5
	Quantity: 8000PCS	

Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2025.01.10	2025.01.10	3.0	New File	/	Ding	